

1. Do not give this product a strong press-force or a mechanical shock, because such mechanical forces may cause cracking or chipping of this ceramic product.
2. Rapid cooling or heating during soldering is not recommended such treatment may destroy the element.
3. Resin coating  
Please select a resin material with minimum hardness. The shrinkage of the resin at heat treatment should be much less in order not to apply much stress to the product.
4. Location on Printed Circuit Board (PC Board)  
Choose a mounting position that minimizes the stress imposed on the chip during flexing or bending of the board.

